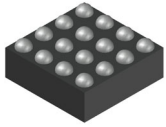


MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

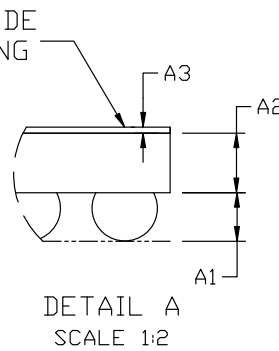
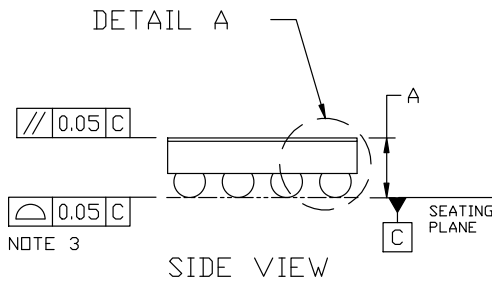
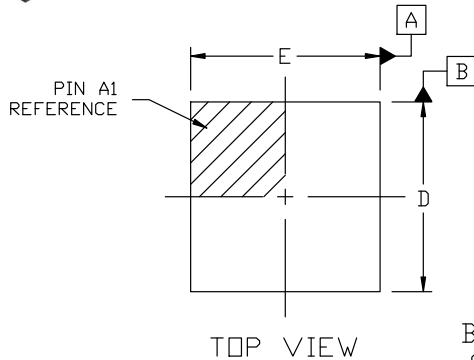


WLCSP16 1.560x1.560x0.470
CASE 567UX
ISSUE O

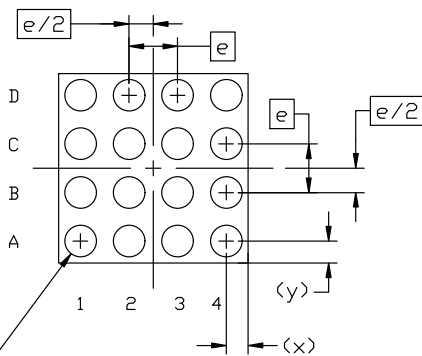
DATE 29 NOV 2022

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.

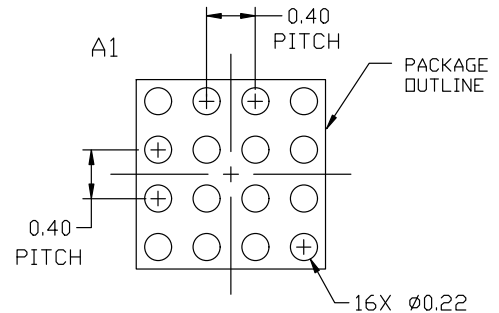


DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.452	0.490	0.528
A1	0.178	0.198	0.218
A2	0.252	0.267	0.282
A3	0.022	0.025	0.028
b	0.240	0.260	0.280
D	1.530	1.560	1.590
E	1.530	1.560	1.590
e	0.400 BSC		
x	0.180 BSC		
y	0.180 BSC		



\oplus	0.05 (M)	C	A	B
	0.03 (M)	C		

BOTTOM VIEW



RECOMMENDED MOUNTING FOOTPRINT*

* For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code
A = Assembly Location
YY = Year
WW = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	WLCSP16 1.560x1.560x0.470	PAGE 1 OF 1

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